

This listing of claims replaces all prior versions, and listings, of claims in this application.

**Listing of Claims:**

1. (Currently Amended) A semiconductor device comprising:  
a semiconductor chip;  
[an] a first external connection electrode connected to the chip; [and]  
a second external connection electrode connected to the chip; and  
a resin package [which] that covers the chip and has a mounting surface;  
wherein each of the first and second electrodes includes a thick portion and a thin portion,  
the thick portion being exposed to outside only at the mounting surface of the package, the thick  
portion being not exposed at any other surface of the package.
2. (Currently Amended) The semiconductor device according to claim 1, wherein the  
first electrode has a flat upper surface for mounting the chip, the thick portion of the first  
electrode including a downward projection extending from the upper surface to the mounting  
surface of the package.
3. (Previously Amended) The semiconductor device according to claim 2, wherein the  
projection includes a bottom surface exposed to outside at the mounting surface of the package  
and four side surfaces entirely covered with the package.
4. (Original) The semiconductor device according to claim 1, wherein the thick portion  
and the thin portion are formed of a same material and integral with each other.
5. (Currently Amended) The semiconductor device according to claim 1, wherein the  
first electrode includes two thick portions spaced from each other and a thin portion connecting

the thick portions, both of the two thick portions being exposed to outside only at the mounting surface of the package.

6. (Original) The semiconductor device according to claim 1, wherein the package includes a side surface different from the mounting surface, the thin portion including a horizontal extension exposed to outside t the side surface of the package.

7. (Original) The semiconductor device according to claim 6, wherein the horizontal extension is spaced from the mounting surface of the package.

8. (Cancelled)

9. (Currently Amended) The semiconductor device according to claim [8] 1, wherein the first external connection electrode include a first flat surface for mounting the chip, the [additional] second external connection electrode including a second flat surface for connection to the chip via a wire, the first surface and the second surface being flush with each other.

10. (Cancelled)

11. (New) A semiconductor device comprising:

a semiconductor chip;

a plurality of external connection electrodes connected to the chip; and

a resin package that covers the chip and has a mounting surface;

wherein each of said plurality of external connection electrodes includes a thick portion and a thin portion, the thick portion being exposed to outside only at the mounting surface of the package, the thick portion being spaced apart from any other surface of the package so as not to be exposed at said any other surface of the package.